

Atty. Docket No. CPAC 1029-5
Appl. No. 10/681,583



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/681,583

Filed: October 8, 2003

Title: (Amended) **Semiconductor multi-package
module having inverted second package
stacked over die-up flip-chip ball grid array
(BGA) package**

Examiner: Alonzo CHAMBLISS

Group Art Unit: 2814

Date: 6 December 2005.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 6 December 2005.

Signed

Paula Faulk Hurley

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

Responsive to the Office action mailed November 9, 2005, please amend this application as follows.

Amendments to the Specification begin on page 2 of this paper.

There are no amendments to the claims. A **Listing of Claims** is included for the Examiner's convenience, beginning on page 5 of this paper.

Amendments to the Drawings begin on page 10 of this paper and include both attached replacement sheets and annotated sheets showing changes.

Remarks begin on page 11 of this paper.

An **Appendix** including amended drawing figures is attached following page 14 of this paper.